## **Financial Announcement**

## FY2022 Ended March31, 2022

May 13, 2022 TAZMO Co., Ltd.



## Company Info

**TAZMO** 

Head office

Company name TAZMO Co., Ltd.

Established February 26, 1972

Head office 5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan

Capital ¥2,724 Billion

Employees Non-consolidated: 354

Consolidated: 1,099

(as of December 31, 2021)

Business Development, Manufacturing and Sales of

Content Semiconductor Manufacturing Equipment,

Clean Transfer System, LCD Manufacturing Equipment,

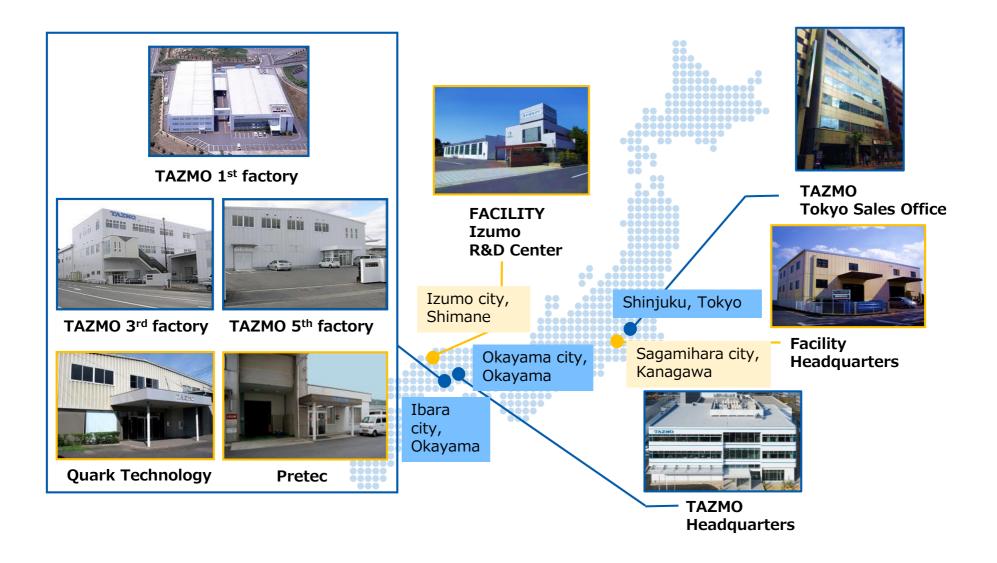
UV Laser Equipment, Plating Equipment, Mold • Resin Molding,

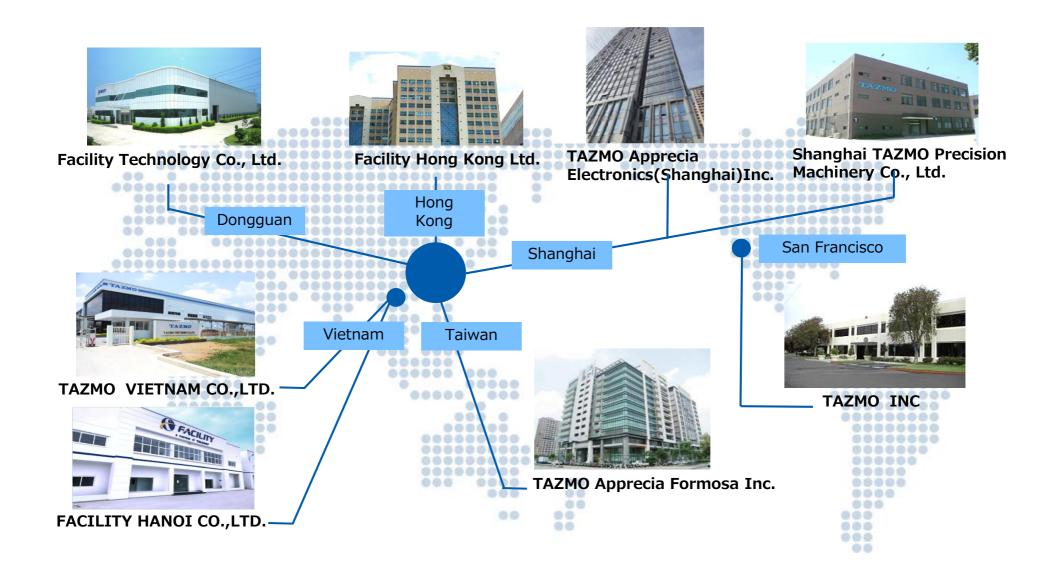
Plating/Circuit formation Equipment for PCB

1972	TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment.
1980	Began production of molding dies, including injection molding dies.
	Completed development of Fully-automated Photo Resist Coater; production and sales started.
1989	Developed TFT Full-color filter manufacturing system; production and sales started.
1990	Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama
	Developed and produced Ultra Compact Transfer System for Super Clean Room.
1994	Began production and sales of Emboss Carrier Tape.
1995	Began production of injection Molding Products.
2001	Developed "CS13" series Photo Resist Coater specialized for a thicker film application; production and sales started.
2004	Listed on the JASDAQ market.
2008	Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam.



2009	Developed 10 <sup>th</sup> generation compatible full-color filter manufacturing system; production and sales started.
	Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment.
2013	Apprecia Technology Inc. became our wholly owned subsidiary company.
	VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam.
2015	Capital increased to 1,616,830,000 yen through third-party allocation of shares.
2017	Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company.
2018	[March] Listed on the Second Section of the Tokyo Stock Exchange
	【September】Listed on the First Section of the Tokyo Stock Exchange
2019	Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama
2020	Merged with Apprecia Technology Inc.





## Semiconductor Manufacturing Equipment Business Unit

Development, Manufacturing and Sales of chemical Coating • Develop equipment and Temporary Bonding • De-bonding equipment for Silicon Thinning used for Semiconductor Manufacturing





#### Transfer Business Unit

Development, Manufacturing and Sales of silicon wafer Transfer robot, Pre-aligner and customized unit of these components used for Semiconductor Manufacturing Equipment.





### Cleaner Business Unit

Development, Manufacturing and Sales of Silicon Wafer Cleaner, Slurry Distribution system and Phosphoric Acid Reclaim System used for Semiconductor Manufacturing.









### Coater Business Unit

Development, Manufacturing and Sales of chemical coating system for glass substrate like Liquid Crystal Display(LCD)





# Precision molding dies and moldings business

Manufacture and sale of injection molds for electronic equipment parts, resin molded products such as connectors using the injection molds, and embossed carrier tapes

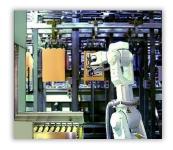




## Surface treatment equipment business

Development, Manufacturing and Sales of Plating/Circuit formation Equipment for Printed Circuit Board.

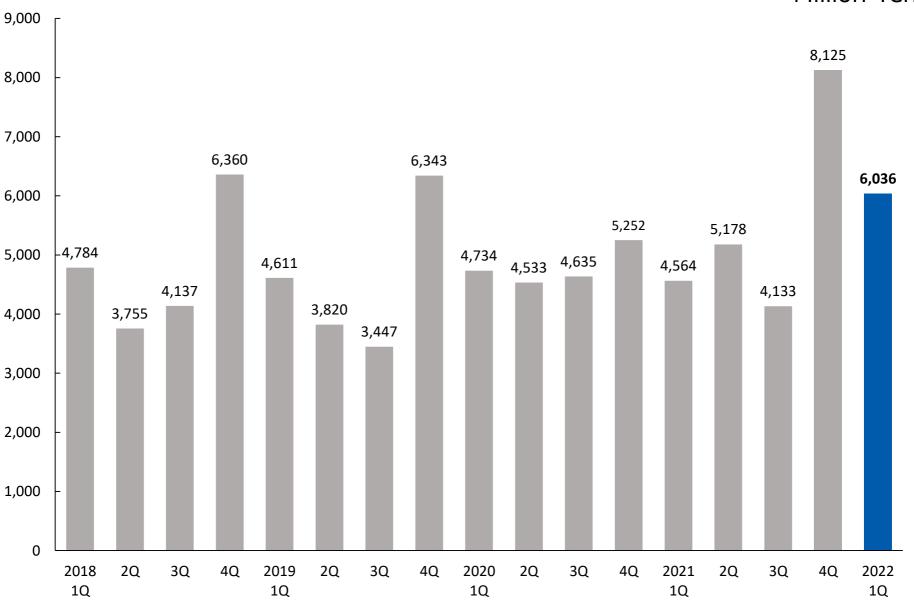




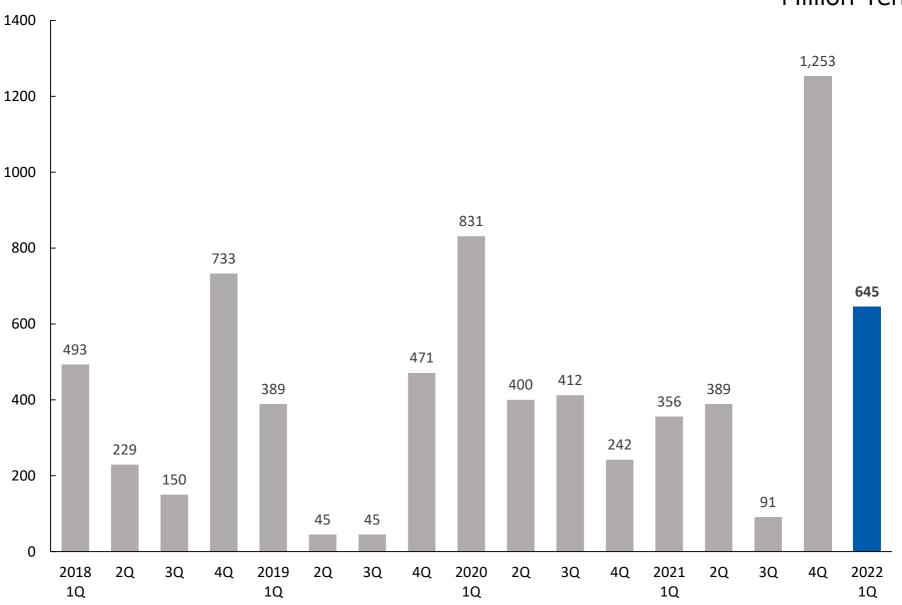


Million Yen	FY2021	FY2022	Sales ratio (%)	Estimates	Achievement ratio (%)
Net sales	4,564	6,036	_	25,338	23.8
<b>Gross profit</b>	1,213	1,692	28.0	_	<del>_</del>
SG&A expenses	857	1,046	17.3	_	_
Operating income	356	645	10.7	2,555	25.2
Ordinary income	413	754	12.5	2,503	30.1
Net income	279	534	8.9	1,731	30.8











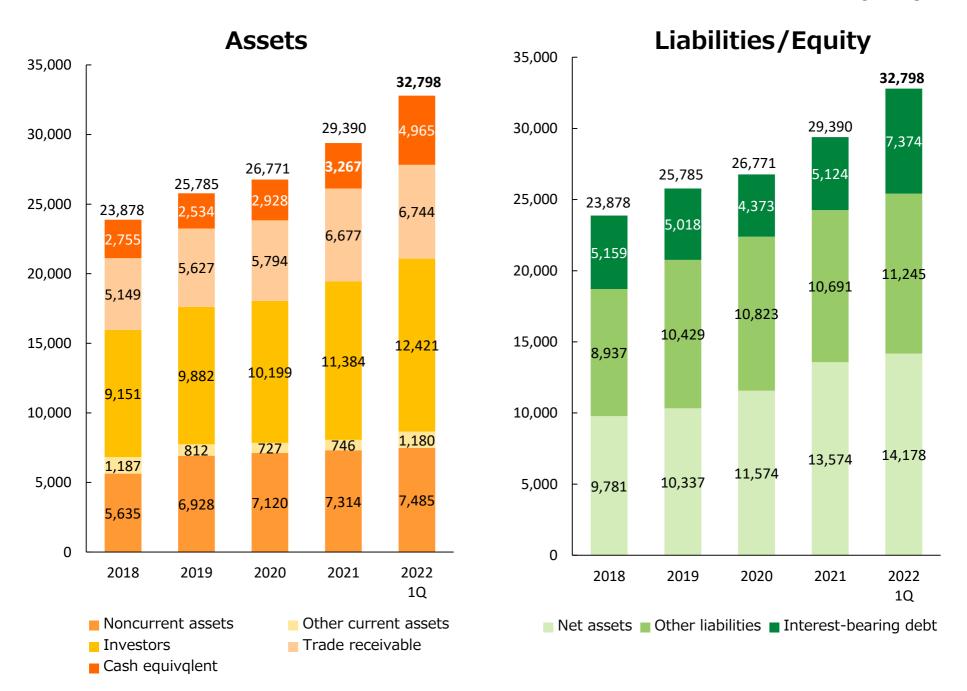
	FY2021	FY2022 1Q	Changes
Current assets	22,075	25,313	3,237
Property, plant and equipment	5,870	5,973	102
Intangible assets	147	203	55
Investments and other assets	1,295	1,308	13
Total assets	29,390	32,798	3,408
Current liabilities			
Noncurrent liabilities	13,457	14,088	631
Net assets	2,357	4,531	2,173
Equity ratio	13,574	14,178	604
Current assets	45.5%	42.5%	△3.0P

## Consolidated B/S Major changes



Major changes						
Assets						
	FY2022 1Q	vs. FY2021				
Cash and deposits	4,965	1,698				
Notes receivable trade/Accounts receivable trade	5,450	△24				
Electronically recorded monetary claims-operating	1,293	91				
Raw materials	12,421	1,037				
Liabilities						
	FY2022 1Q	vs. FY2021				
Electronically recorded obligations- operating	2,970	481				
Advances received (Contract liability)	2,823	△547				
Short-term borrowings	3,534	363				
Liability related to paid transactions	458	458				
Long-term borrowings	3,839	2,186				





# Segment information



Million Yen	FY2021 1Q	FY2022 1Q	Sales ratio (%)	Estimates	Achievement ratio (%)
Net sales	4,564	6,036	_	25,338	23.8
Process equipment business	3,568	4,842	80.2	19,857	24.3
Semiconductor equipment	383	1,150	19.1	6,003	19.1
Transfer equipment	1,382	1,812	30.0	6,122	29.5
Cleaning equipment	938	287	4.8	3,037	9.4
Coater	864	1,591	26.3	4,693	33.9
Precision molding dies and plastic moldings business	369	404	6.7	1,701	23.7
Surface treatment equipment business	626	789	13.1	3,779	20.8

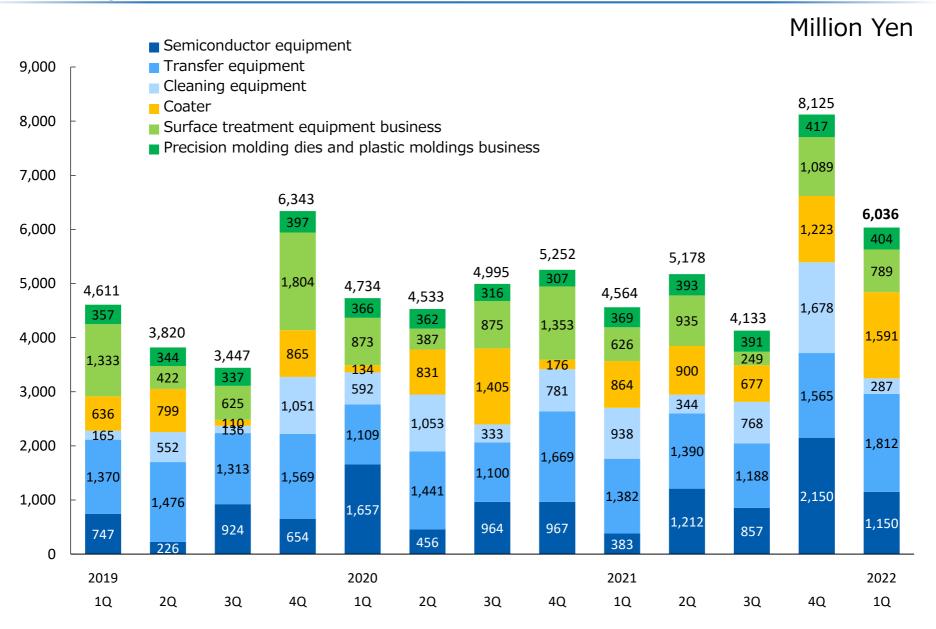
# Segment information



Million Yen	FY2021 1Q	FY2022 1Q	Sales ratio (%)	Estimates	Achieveme nt ratio (%)
Operating income	356	645	10.7	2,555	25.2
Process equipment business	299	580	9.6	2,317	25.0
Precision molding dies and plastic moldings business	32	22	0.4	57	38.5
Surface treatment equipment business	24	64	1.1	180	35.5
Elimination of inter- segment transactions	0	△21	_	_	_

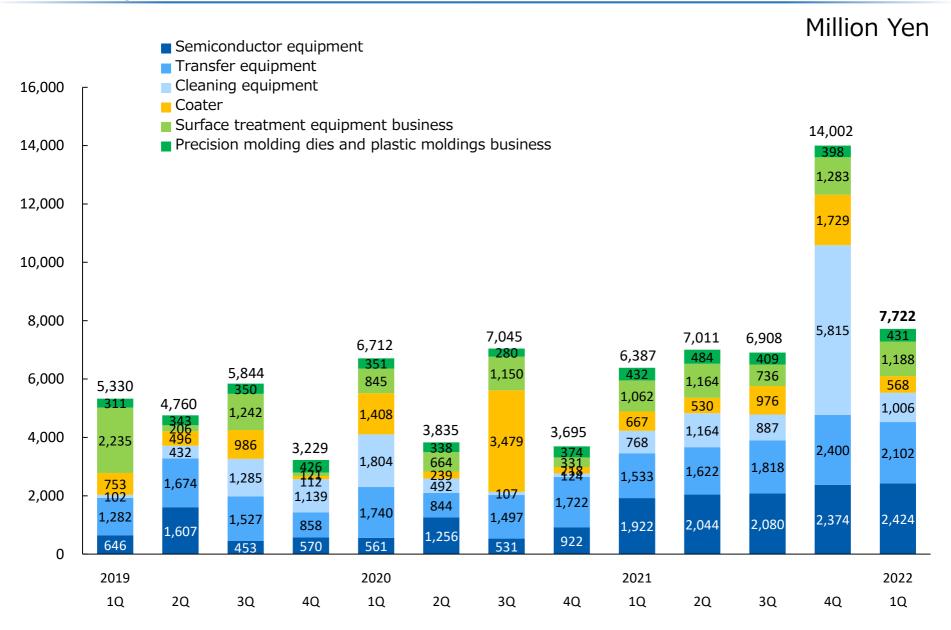
## History of Net Sales





## History of Sales Orders

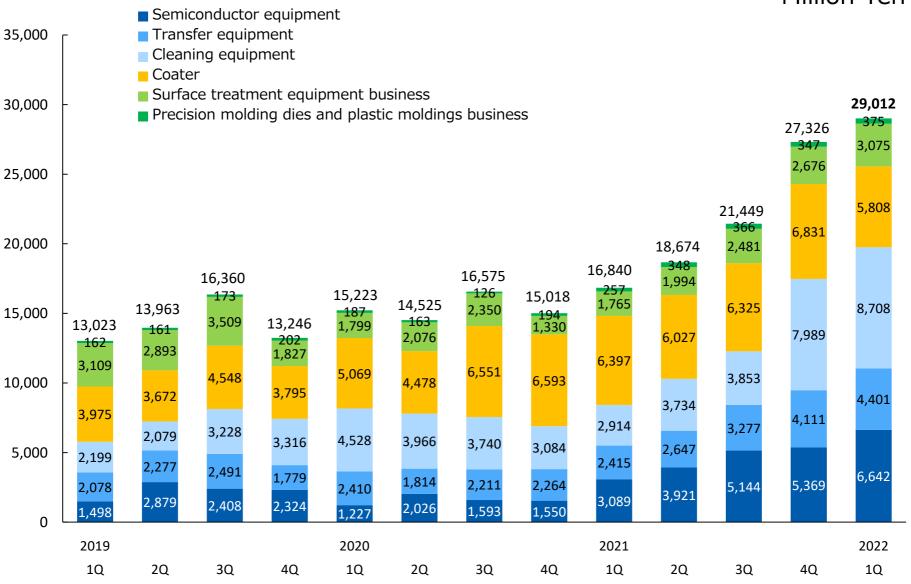




## History of Order Backlog







# TAZMO